L Number	Hits	Search Text	DB	Time stamp
-	2	(("6258220") or ("6508920")).PN.	USPAT	2004/09/09 15:06
-	2	1 1 1	USPAT	2004/08/31 08:56
-	2	wafer ((("6258220") or ("6508920")).PN.) and wafer and anneal\$4	USPAT	2004/08/31 08:56
_	2	((("6258220") or ("6508920")).PN.) and wafer and (first with second) and	USPAT	2004/08/31 08:57
	2	anneal\$4 ((("6258220") or ("6508920")).PN.) and	USPAT	2004/08/31
		wafer and (first with second) and anneal\$4 and cool		08:57
_	0	((("6258220") or ("6508920")).PN.) and wafer and (first with second) and	USPAT	2004/08/31 08:57
_	2	anneal\$4 and cool and hour ((("6258220") or ("6508920")).PN.) and wafer and (first with second) and	USPAT	2004/08/31 08:57
_	2	anneal\$4 and cool and time ((("6258220") or ("6508920")).PN.) and wafer and (first with second) and anneal\$4 and cool and time and	USPAT	2004/08/31
_	527	temperature 438/758.ccls.	USPAT	2004/08/31
-	38	438/758.ccls. and (wafer with anneal\$4)	USPAT	09:06 2004/08/31 09:07
-	16	438/758.ccls. and (wafer with anneal\$4) and (first with second) and anneal	USPAT	2004/08/31 09:07
-	16	438/758.ccls. and (wafer with anneal\$4) and (first with second) and anneal and	USPAT	2004/08/31 09:07
-	6	temperature 438/758.ccls. and (wafer with anneal\$4) and (first with second) and anneal and temperature and cool\$4	USPAT	2004/09/02 08:23
-	6	438/758.ccls. and (wafer with anneal\$4) and (first with second) and anneal and	USPAT	2004/08/31 10:49
_	596	temperature and cool\$4 and time 438/660.ccls.	USPAT	2004/08/31
-	82	438/660.ccls. and wafer and (first with second and anneal)	USPAT	2004/08/31 10:50
-	80	438/660.ccls. and wafer and (first with second and anneal) and temperature	USPAT	2004/08/31 10:50
-	77	438/660.ccls. and wafer and (first with second and anneal) and temperature and	USPAT	2004/08/31 10:50
_	61	time 438/660.ccls. and wafer and (first with second and anneal) and temperature and	USPAT	2004/08/31 10:50
	20	time and low	USPAT	2004/08/31 10:51
_	0	time and low and "400" 438/660.ccls. and wafer and (first with second and anneal) and temperature and	USPAT	2004/08/31
_	40	time and low and "0-400" 438/660.ccls. and wafer and (first with	USPAT	2004/08/31
		second and anneal) and temperature and time and low and "200"	USPAT	10:52
-	24	438/660.ccls. and wafer and (first with second and anneal) and temperature and time and low and "300"	JULIA	10:53
-	6	438/660.ccls. and wafer and (first with second and anneal) and temperature and time and low and "300" and stress and	USPAT	2004/08/31 10:53
-	20	copper 438/795.ccls. and (wafer with anneal\$4) and (first with second) and anneal and	USPAT	2004/09/02 08:24
		temperature and cool\$4		<u> </u>

	19321	wafer and (first with second and	USPAT;	2004/09/09
_	19321	anneal\$4)	US-PGPUB;	15:08
	[annearys;	EPO; JPO;	1 13.00
	-		DERWENT	1
	7100	fan and /finat with accord and	USPAT;	2004/09/09
_	7189	· · · · · · · · · · · · · · · · · · ·		15:08
		anneal\$4) and (low with temperature)	US-PGPUB;	15:00
			EPO; JPO; DERWENT	
	2067			2004/00/00
-	3267	···· ····	USPAT;	2004/09/09
		anneal\$4) and (low with temperature) and	US-PGPUB;	15:09
		"400"	EPO; JPO;	
			DERWENT	2004/00/00
-	2008	•	USPAT;	2004/09/09
		anneal\$4) and (low with temperature) and	US-PGPUB;	15:09
	["400" and treat\$4	EPO; JPO;	
			DERWENT	0004/00/00
-	135		USPAT;	2004/09/09
		anneal\$4) and (low with temperature) and	US-PGPUB;	15:09
		"400" and treat\$4 and microstructure	EPO; JPO;	ľ
			DERWENT	/ /
-	66		USPAT;	2004/09/09
		anneal\$4) and (low with temperature) and	US-PGPUB;	15:10
		"400" and treat\$4 and microstructure and	EPO; JPO;	
		stress	DERWENT	
-	15	1	USPAT;	2004/09/09
		anneal\$4) and (low with temperature) and	US-PGPUB;	15:10
		"400" and treat\$4 and microstructure and	EPO; JPO;	
1		stress and migration	DERWENT	1

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